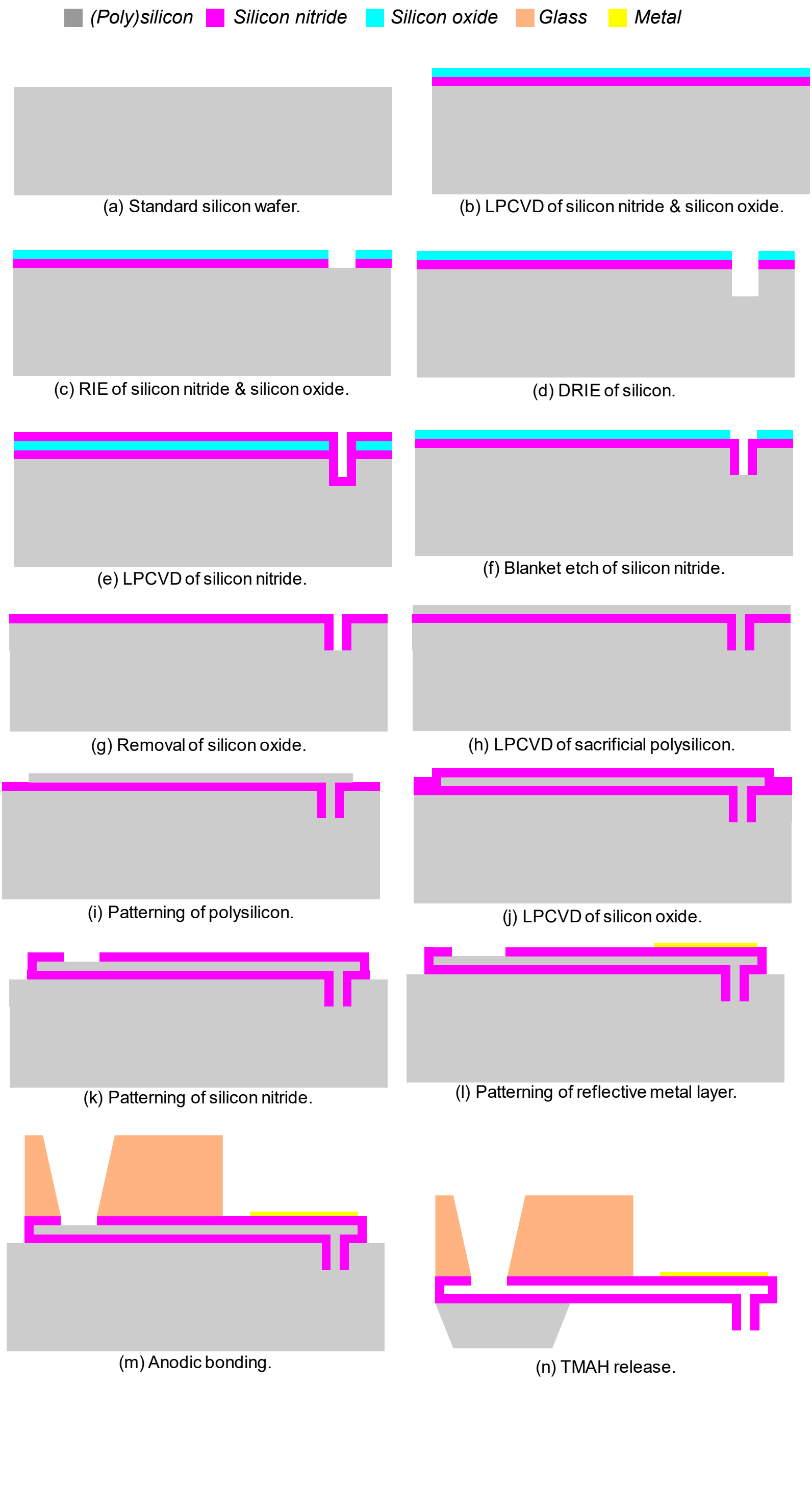
A



(a) Standard silicon wafer.

(b) LPCVD of silicon nitride & silicon oxide.

(c) RIE of silicon nitride & silicon oxide.

(d) DRIE of silicon.

(e) LPCVD of silicon nitride.

(f) Blanket etch of silicon nitride.

(g) Removal of silicon oxide.

(h) LPCVD of sacrificial polysilicon.

(i) Patterning of polysilicon.

(j) LPCVD of silicon oxide.

(k) Patterning of silicon nitride.

(l) Patterning of reflective metal layer.

(m) Anodic bonding.

(n) TMAH release.

B